

IN THE CLAIMS:

Please amend the claims as follows:

Claims 1-3 (Cancelled).

Claim 4 (Currently Amended): A method of manufacturing a battery pack having a vessel, a battery mounted in the vessel and a circuit board connected to the battery, comprising:

a step of forming a terminal portion in manufacturing ~~said~~ the circuit board, ~~said~~ the step of forming [a] the terminal portion ~~being to stack~~ including stacking a base layer of copper and a plated layer of gold successively to form the terminal portion,

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glass epoxy resin; and

a step of forming an insulating layer after ~~said~~ the step of forming [a] the terminal portion in manufacturing ~~said~~ the circuit board, ~~said~~ the step of forming [an] the insulating layer ~~being to form~~ including forming [an] the insulating layer in ~~the~~ another ~~other~~ area than ~~the~~ an area where ~~said~~ the terminal portion is formed,

wherein ~~said~~ the insulating layer is formed so as to cover a peripheral edge of ~~said~~ the plated layer so that the surface of ~~said~~ the circuit board and at least one of the surface of the base layer are not exposed externally, and the insulating layer is made of epoxy

resin; and

a step of mounting an electronic component after the step of forming the insulating layer, the step of mounting the electronic component including mounting the electronic component on given positions of the circuit board by a solder reflow process.

Claims 5-6 (Cancelled).

Claim 7 (Currently Amended): A method of manufacturing a battery pack according to claim 4, further comprising the steps of:

forming a base layer of a copper pattern on a surface of an insulating board;
forming a plated layer so as to cover the entire base layer by selective plating; and
forming an the insulating layer on said the plated layer and patterning said the insulating layer so that only a portion of said the plated layer is exposed externally.

Claims 8-10 (Cancelled).

Claim 9 (New): A method of manufacturing a battery pack according to claim 4, further comprising the step of:

stamping out a rigid-type integral board along each area thereof, on which the circuit board is to be formed, with a mold.

Claim 10 (New): A method of manufacturing a battery pack having a vessel, a battery mounted in the vessel and a circuit board connected to the battery, the method comprising:

preparing a rigid type integral board;

forming terminal portions in a first area of the rigid-type integral board, on which the circuit board is to be formed, by successively stacking a base layer made of copper and a plated layer made of gold;

forming an insulating layer in the first area other than a second area where the terminal portions are formed;

mounting an electronic component on given positions of the first area by a solder reflow process; and

stamping out the rigid-type integral board along the first area with a mold, thereby providing the circuit board,

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glassy epoxy resin, and

wherein the insulating layer is formed so as to cover a peripheral edge of the plated layer so that a surface of the base is not exposed externally.